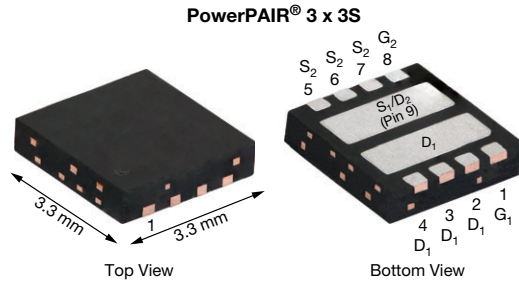


Dual N-Channel 30 V (D-S) MOSFETs



FEATURES

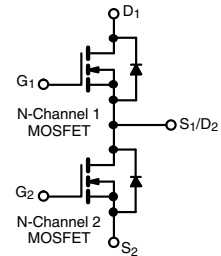
- TrenchFET® Gen IV power MOSFETs
- 100 % R_g and UIS tested
- Optimized Q_{gs}/Q_g ratio improves switching characteristics
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- CPU core power
- Computer / server peripherals
- POL
- Synchronous buck converter
- Telecom DC/DC



PRODUCT SUMMARY		
	CHANNEL-1	CHANNEL-2
V _{DS} (V)	30	30
R _{DS(on)} max. (Ω) at V _{GS} = 10 V	0.0055	0.0058
R _{DS(on)} max. (Ω) at V _{GS} = 4.5 V	0.0073	0.0077
Q _g typ. (nC)	8.4	9.2
I _D (A)	61 ^a	60 ^a
Configuration	Dual	

ORDERING INFORMATION	
Package	PowerPAIR 3 x 3S
Lead (Pb)-free and halogen-free	SiZ200DT-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	CHANNEL-1	CHANNEL-2	UNIT	
Drain-source voltage	V _{DS}	30	30	V	
Gate-source voltage	V _{GS}	+20, -16	+20, -16		
Continuous drain current (T _J = 150 °C)	I _D	T _C = 25 °C	61 ^a	60 ^a	A
		T _C = 70 °C	49	48	
		T _A = 25 °C	22 ^{b, c}	22 ^{b, c}	
		T _A = 70 °C	18 ^{b, c}	17 ^{b, c}	
Pulsed drain current (100 μs pulse width)	I _{DM}	130	130	A	
Continuous source drain diode current	I _S	T _C = 25 °C	27		27
		T _A = 25 °C	3.6 ^{b, c}	3.6 ^{b, c}	
Single pulse avalanche current	I _{AS}	15	15	mJ	
Single pulse avalanche energy	E _{AS}	11	11		
Maximum power dissipation	P _D	T _C = 25 °C	33	33	W
		T _C = 70 °C	21	21	
		T _A = 25 °C	4.3 ^{b, c}	4.3 ^{b, c}	
		T _A = 70 °C	2.8 ^{b, c}	2.8 ^{b, c}	
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150		°C	
Soldering recommendations (peak temperature) ^d		260			

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	CHANNEL-1		CHANNEL-2		UNIT	
		TYP.	MAX.	TYP.	MAX.		
Maximum junction-to-ambient ^{b, f}	R _{thJA}	23	29	23	29	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	3	3.8	3	3.8		

Notes

- T_C = 25 °C
- Surface mounted on 1" x 1" FR4 board
- t = 10 s
- See solder profile (www.vishay.com/doc?73257). The PowerPAIR 3 x 3S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 64 °C/W for channel-1 and 64 °C/W for channel-2



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT		
Static								
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	Ch-1	30	-	-	V	
		V _{GS} = 0 V, I _D = 250 μA	Ch-2	30	-	-		
V _{DS} Temperature coefficient	ΔV _{DS} /T _J	I _D = 250 μA	Ch-1	-	13	-	mV/°C	
		I _D = 250 μA	Ch-2	-	18	-		
V _{GS(th)} Temperature coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA	Ch-1	-	-5.2	-	mV/°C	
		I _D = 250 μA	Ch-2	-	-5.1	-		
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	Ch-1	1.1	-	2.4	V	
		V _{DS} = V _{GS} , I _D = 250 μA	Ch-2	1.1	-	2.4		
Gate source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = +20 V, -16 V	Ch-1	-	-	± 100	nA	
		V _{DS} = 0 V, V _{GS} = +20 V, -16 V	Ch-2	-	-	± 100		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	Ch-1	-	-	1	μA	
		V _{DS} = 30 V, V _{GS} = 0 V	Ch-2	-	-	1		
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	Ch-1	-	-	5		
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	Ch-2	-	-	5		
On-state drain current ^b	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-1	10	-	-	A	
		V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-2	10	-	-		
Drain-source on-state resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A	Ch-1	-	0.0045	0.0055	Ω	
		V _{GS} = 10 V, I _D = 10 A	Ch-2	-	0.0048	0.0058		
		V _{GS} = 4.5 V, I _D = 7 A	Ch-1	-	0.0057	0.0073		
		V _{GS} = 4.5 V, I _D = 7 A	Ch-2	-	0.0060	0.0077		
Forward transconductance ^b	g _{fs}	V _{DS} = 10 V, I _D = 30 A	Ch-1	-	118	-	S	
		V _{DS} = 10 V, I _D = 30 A	Ch-2	-	105	-		
Dynamic ^a								
Input capacitance	C _{iss}	Channel-1 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	Ch-1	-	1510	-	pF	
			Ch-2	-	1600	-		
Output capacitance	C _{oss}		Ch-1	-	590	-		
			Ch-2	-	620	-		
Reverse transfer capacitance	C _{rss}		Channel-2 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	Ch-1	-	28		-
				Ch-2	-	27		-
C _{rss} /C _{iss} ratio		Ch-1		-	0.019	0.040		
		Ch-2		-	0.017	0.035		
Total gate charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A		Ch-1	-	18.3	28	nC
		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A		Ch-2	-	20	30	
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	Ch-1	-	8.4	13		
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	Ch-2	-	9.2	14		
Gate-source charge	Q _{gs}	Channel-1 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	Ch-1	-	3.7	-		
			Ch-2	-	4.5	-		
Gate-drain charge	Q _{gd}		Channel-2 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	Ch-1	-	1	-	
				Ch-2	-	1	-	
Output charge	Q _{oss}			V _{DS} = 15 V, V _{GS} = 0 V	Ch-1	-	17	-
				V _{DS} = 15 V, V _{GS} = 0 V	Ch-2	-	18	-
Gate resistance	R _g	f = 1 MHz		Ch-1	0.28	1.4	2.8	Ω
				Ch-2	0.2	1	2	



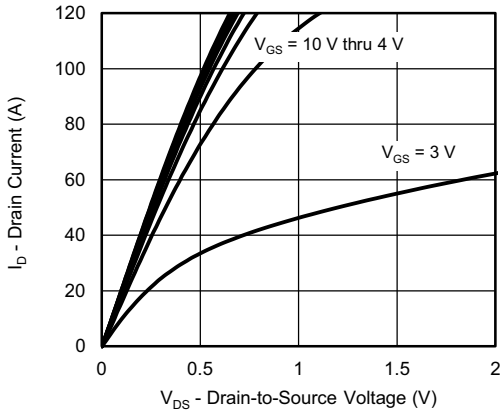
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Dynamic ^a							
Turn-on delay time	t _{d(on)}	Channel-1 V _{DD} = 15 V, R _L = 3 Ω I _D ≅ 5 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	11	20	ns
			Ch-2	-	11	20	
Rise time	t _r		Ch-1	-	5	10	
			Ch-2	-	5	10	
Turn-off delay time	t _{d(off)}	Channel-2 V _{DD} = 15 V, R _L = 3 Ω I _D ≅ 5 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	23	45	
			Ch-2	-	23	45	
Fall time	t _f		Ch-1	-	5	10	
			Ch-2	-	5	10	
Turn-on delay time	t _{d(on)}	Channel-1 V _{DD} = 15 V, R _L = 3 Ω I _D ≅ 5 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	17	35	
			Ch-2	-	20	40	
Rise time	t _r		Ch-1	-	40	80	
			Ch-2	-	42	80	
Turn-off delay time	t _{d(off)}	Channel-2 V _{DD} = 15 V, R _L = 3 Ω I _D ≅ 5 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	23	45	
			Ch-2	-	25	50	
Fall time	t _f		Ch-1	-	7	15	
			Ch-2	-	10	20	
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I _S	T _C = 25 °C	Ch-1	-	-	27	A
			Ch-2	-	-	27	
Pulse diode forward current (t = 100 μs)	I _{SM}		Ch-1	-	-	130	
			Ch-2	-	-	130	
Body diode voltage	V _{SD}	I _S = 5 A, V _{GS} = 0 V	Ch-1	-	0.8	1.2	V
		I _S = 5 A, V _{GS} = 0 V	Ch-2	-	0.8	1.2	
Body diode reverse recovery time	t _{rr}		Ch-1	-	35	70	ns
			Ch-2	-	35	70	
Body diode reverse recovery charge	Q _{rr}	Channel-1 I _F = 5 A, di/dt = 100 A/μs, T _J = 25 °C	Ch-1	-	25	50	nC
			Ch-2	-	25	50	
Reverse recovery fall time	t _a	Channel-2 I _F = 5 A, di/dt = 100 A/μs, T _J = 25 °C	Ch-1	-	18	-	ns
			Ch-2	-	21	-	
Reverse recovery rise time	t _b		Ch-1	-	17	-	
			Ch-2	-	14	-	

Notes

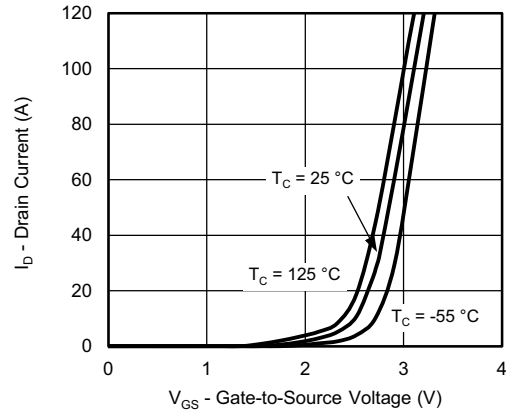
- a. Guaranteed by design, not subject to production testing
- b. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

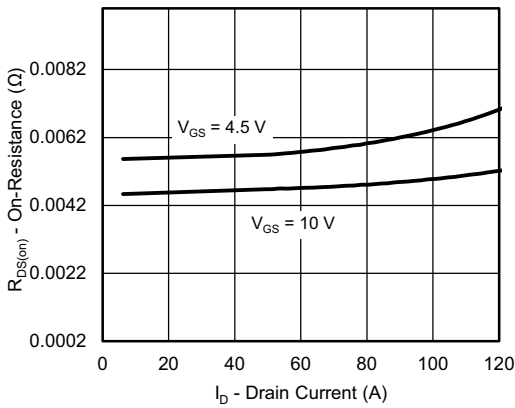
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



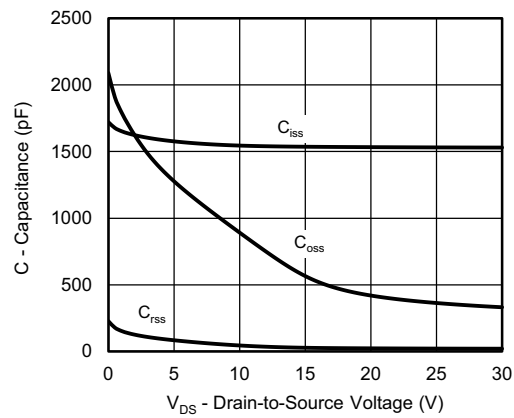
Output Characteristics



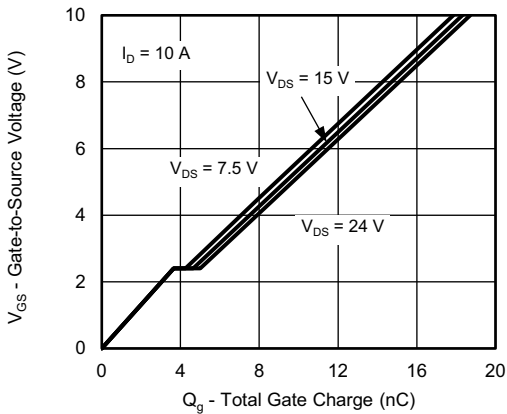
Transfer Characteristics



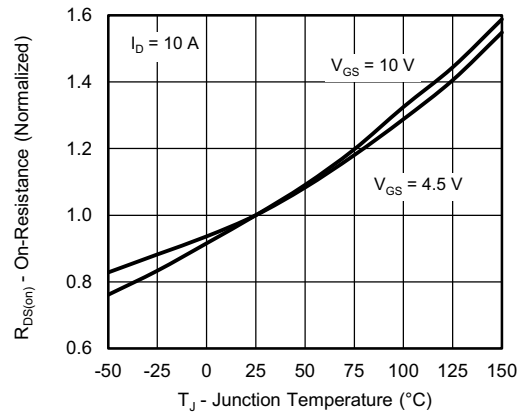
On-Resistance vs. Drain Current



Capacitance

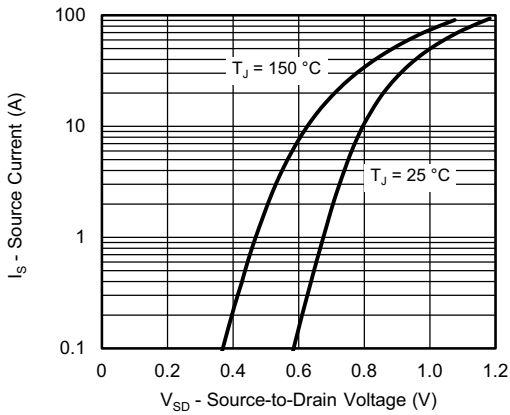


Gate Charge

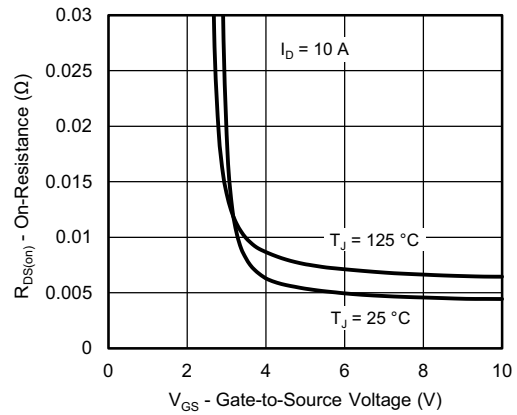


On-Resistance vs. Junction Temperature

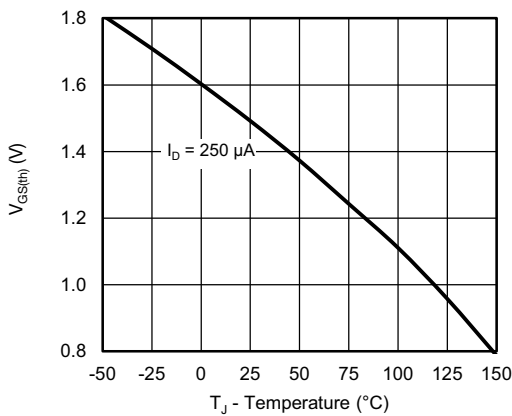
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



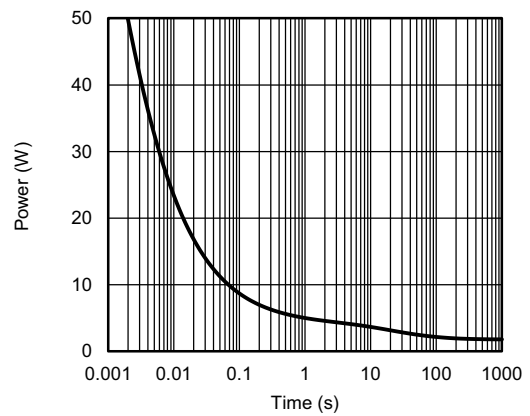
Source-Drain Diode Forward Voltage



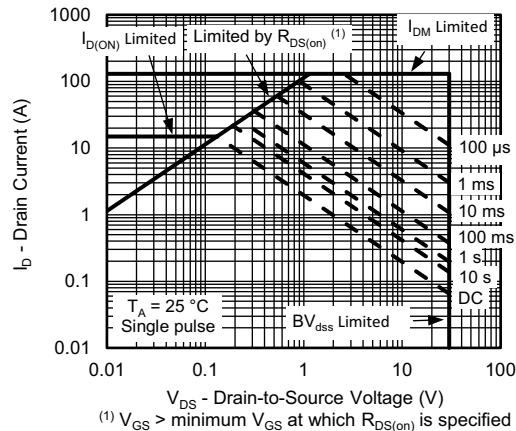
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



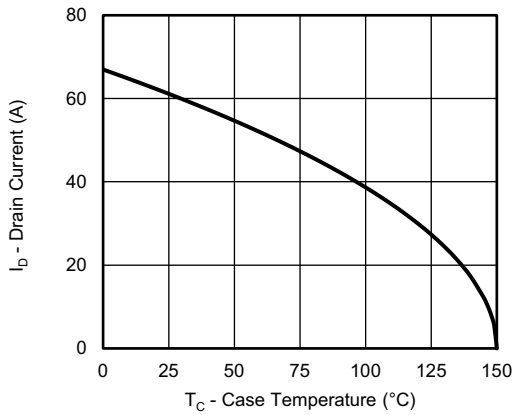
Single Pulse Power, Junction-to-Ambient



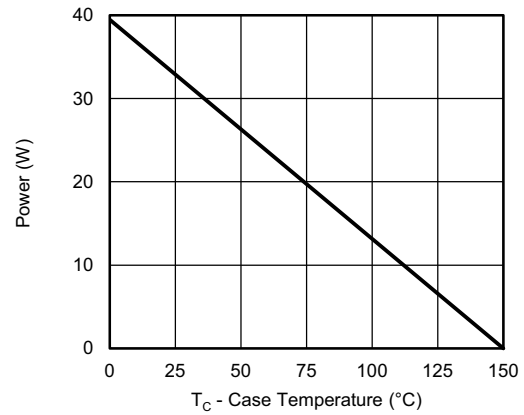
Safe Operating Area, Junction-to-Ambient



CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



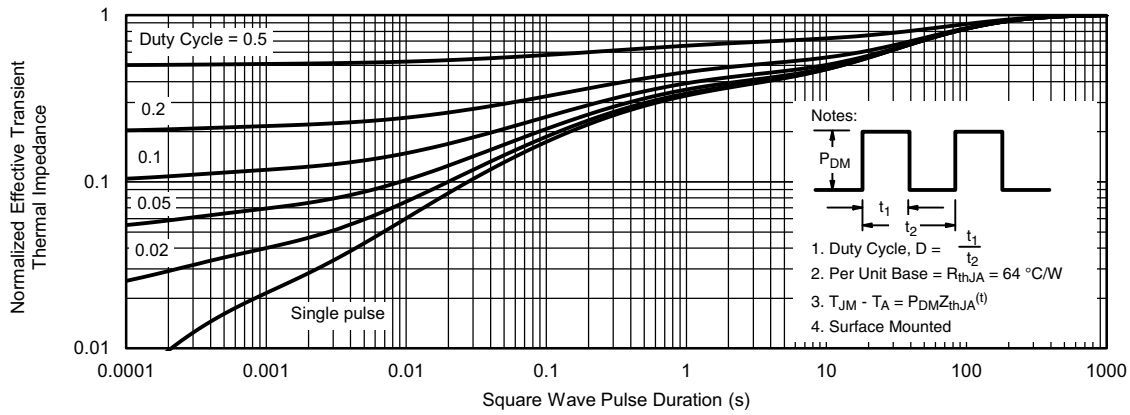
Power, Junction-to-Case

Note

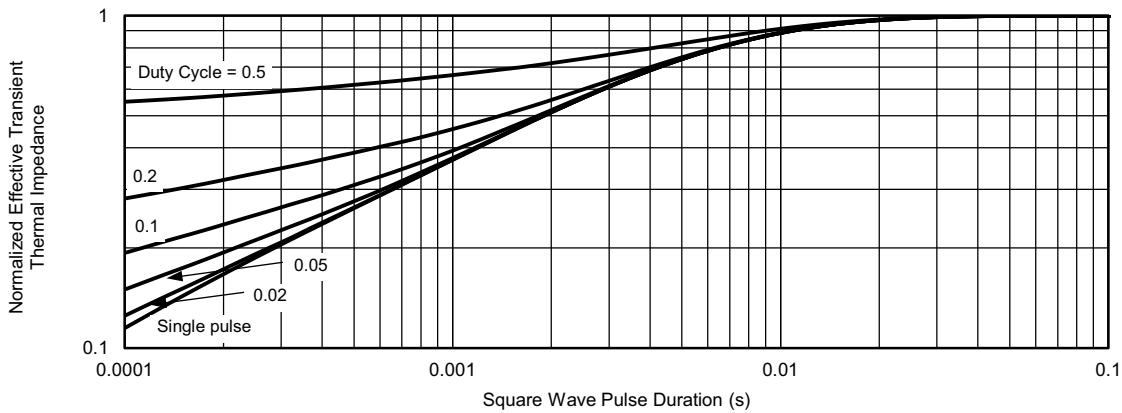
- a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



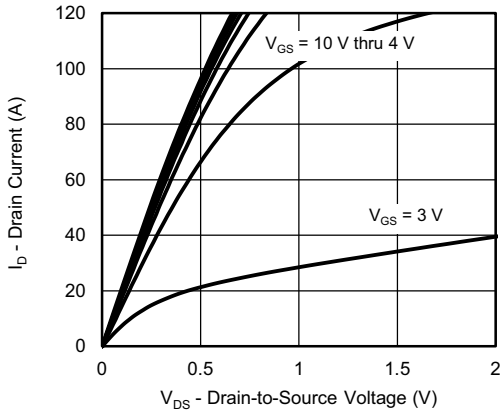
Normalized Thermal Transient Impedance, Junction-to-Ambient



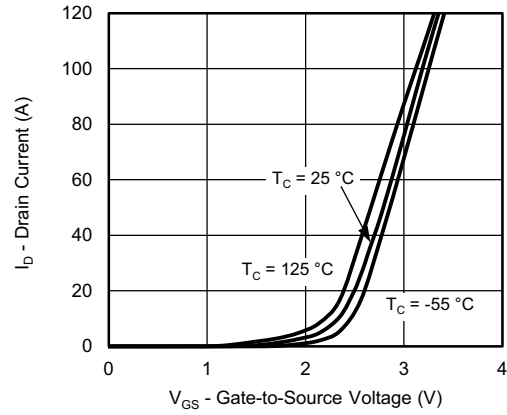
Normalized Thermal Transient Impedance, Junction-to-Case



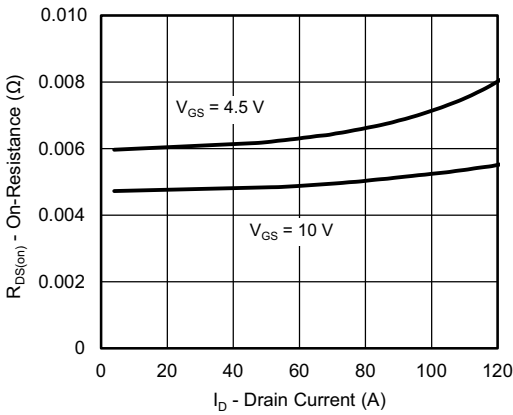
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



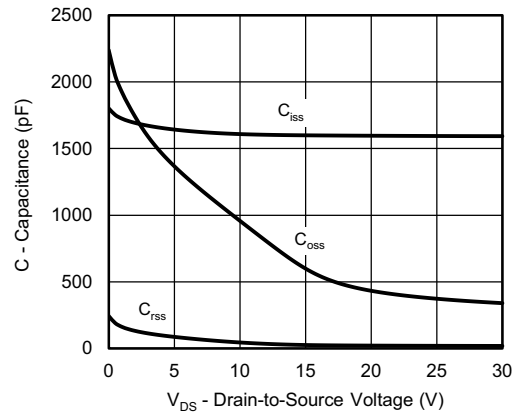
Output Characteristics



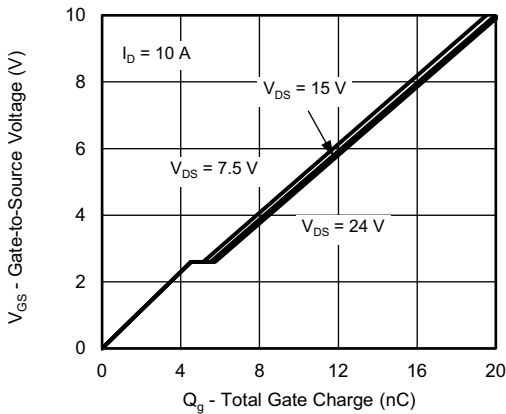
Transfer Characteristics



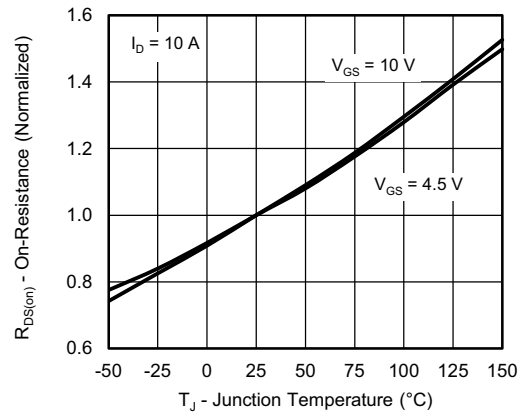
On-Resistance vs. Drain Current



Capacitance



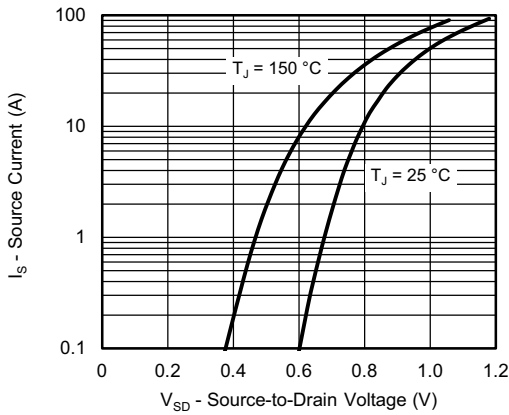
Gate Charge



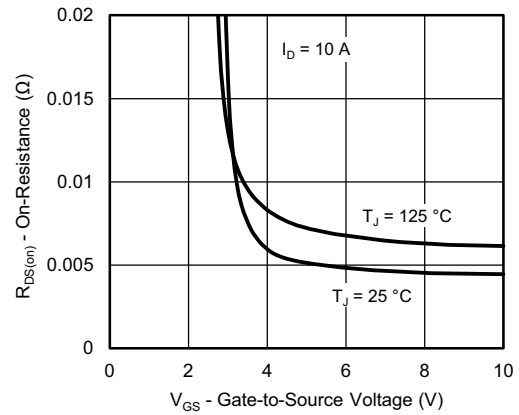
On-Resistance vs. Junction Temperature



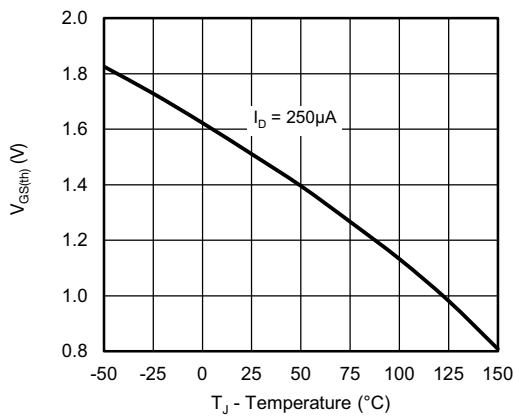
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



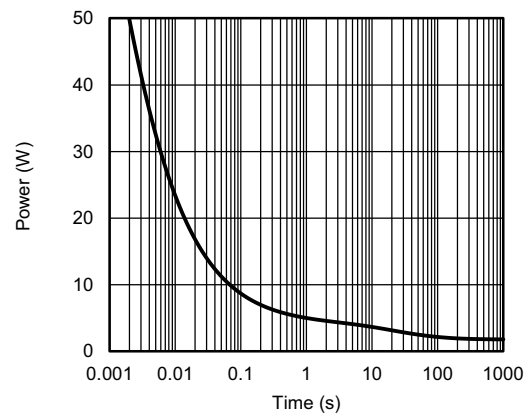
Source-Drain Diode Forward Voltage



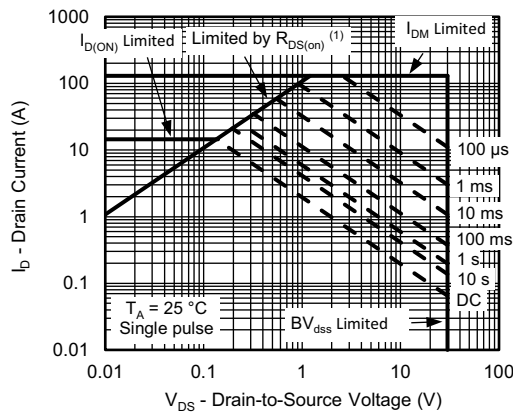
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



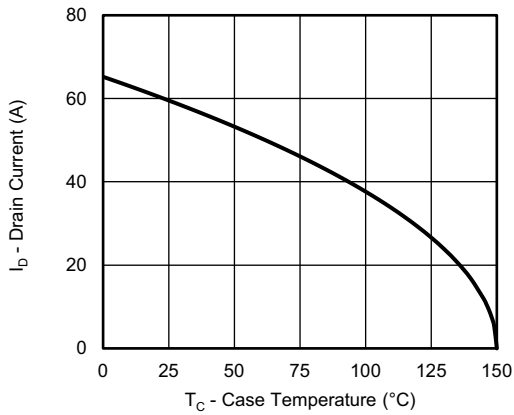
Single Pulse Power, Junction-to-Ambient



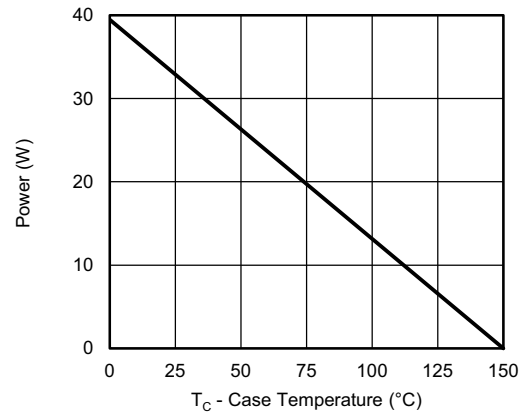
Safe Operating Area, Junction-to-Ambient



CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



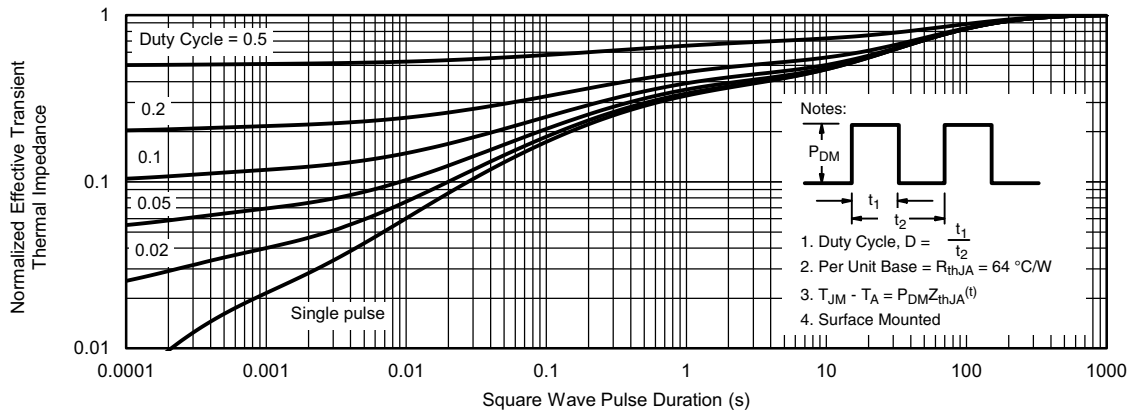
Power, Junction-to-Case

Note

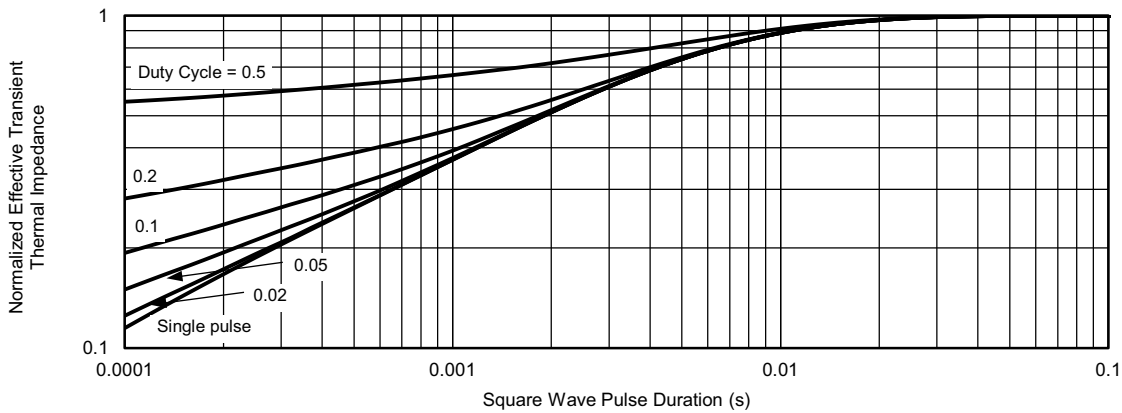
- a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



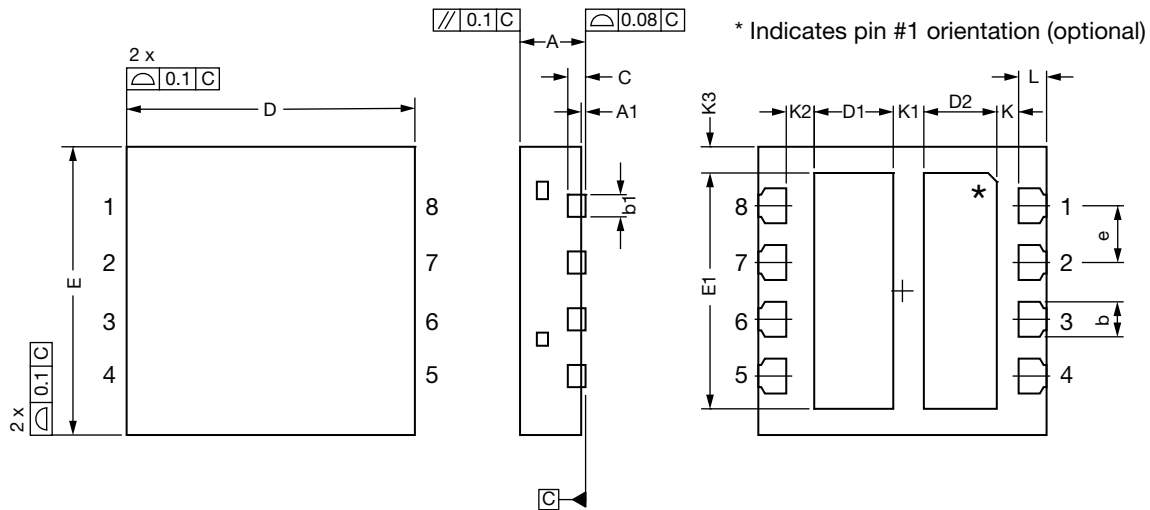
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?75033.

PowerPAIR® 3.3 x 3.3 Case Outline



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	-	0.05	0.000	-	0.002
b	0.35	0.40	0.45	0.014	0.016	0.018
b1	0.20	0.25	0.38	0.008	0.010	0.015
C	0.18	0.20	0.23	0.007	0.008	0.009
D	3.20	3.30	3.40	0.126	0.130	0.134
D1	0.86	0.91	0.96	0.034	0.036	0.038
D2	0.79	0.84	0.89	0.031	0.033	0.035
E	3.20	3.30	3.40	0.126	0.130	0.134
E1	2.65	2.70	2.75	0.104	0.106	0.108
e	0.65 BSC			0.026 BSC		
K	0.25 ref.			0.010 ref.		
K1	0.35 ref.			0.014 ref.		
K2	0.32 ref.			0.013 ref.		
K3	0.30 ref.			0.012 ref.		
L	0.27	0.32	0.37	0.011	0.013	0.015

C18-0564-Rev. A, 14-May-2018
DWG: 6066

Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5M - 1994
- (3) N is the number of terminals; Nd is the number of terminals in X-direction; Ne is the number of terminals in Y-direction
- (4) Dimension b applies to plated terminal and is measured between 0.20 mm and 0.25 mm from terminal tip
- (5) The pin # 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (6) Exact shape and size of this features is optional
- (7) Package warpage max. 0.08 mm
- (8) Applied only for terminals



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